

Room A (605-606)	
13:00	Global Business Council
15:00	
Break	
15:15	Global Business Council
17:15	
17:15-	



Global Business Council

The Global Business Council (GBC) produces IMAPS initiatives that cover many business factors important to corporate IMAPS members. GBC programming develops and communicates the business perspective by producing conferences, forums, and webinars.

Topics: 2.5D and 3D-IC Packaging Technology

Chairperson: Rajen Chanchani, IMAPS Past President, Yasumitsu Orii, ICEP-IAAC 2012 General Chair

■ Speeches

ASET Developments for the movement after Wide IO DRAM

Mr. Hiroaki Ikeda, General Manager, 3D-Integration Technology Research Department Association of Super-Advanced Electronics Technologies / Japan

3D Stacked System Technology and Application Prospective

Dr. Wei-Chung Lo, Director, Industrial Technology Research Institute / Taiwan

TSV Interposer – Materials and Process for Mass Production

Dr. Gu-Sung Kim, Founder & CEO, EPworks Co, Ltd., Professor of Kangnam University / Korea

Design Considerations for 3D IC Integration

Dr. Dim-Lee Kwong, Executive Director, Institute of Microelectronics / Singapore

[As-yet-untitled]

Dr. Frank Murray, CEO, IPDiA / France

3D Integration and Packaging for Systems

Dr. John Knickerbocker, Distinguished Engineer, IBM Watson Research Center / USA

2.5D/3D - Recent Developments in Integration Approaches, Process Capability & Biz Models

Dr. Rajendra D. Pendse, Vice President & Chief Marketing Office, STATS ChipPAC Inc. / USA

2.5D and 3D IC: Product and Supply Chain Readiness

Mr. Rich Rice, Senior Vice President, Sales & Engineering, ASE US Inc. / USA

■ Panel Discussion

Room A (605-608)	
10:00	IMAPS All Asia Conference Special Session
11:15	
Break	
11:25	IMAPS All Asia Conference Special Session
12:25	
Lunch Time	
13:25	Awarding Ceremony
13:50	
13:50	Keynote Speech Future of Packaging from No Value-add in the Past to High Value-add in the Future Prof. Rao R. Tummala, Georgia Institute of Technology
14:50	
Break	
15:00	Keynote Speech Moore's Law is alive and fueling the "Compute Continuum" revolution Dr. Tsuyoshi Abe, Intel K.K.
16:00	
16:00	Keynote Speech 3DIC Integration: A Foundry Perspective Dr. Shang-Yun Hou, Taiwan Semiconductor Manufacturing Company Limited
17:00	
18:30	Welcome Reception Tokyo Bay dinner cruise
21:30	



IMAPS All Asia Conference Special Session

Packaging Technology Trend, Business, and Issues in each region

● Japan

Dr. Fumio Miyashiro, IMAPS ALC President

● US

Ms. E. Jan Vardaman, President at TechSearch International, Inc.

● Europe

Dr. Giovanni Delrosso, IMAPS Europe and ELC President

● China

Prof. Jusheng Ma, Tsinghua University

● Korea

Dr. Gu-Sung Kim, Founder & CEO, EPworks Co, Ltd., Professor of Kangnam University

● India

Dr. Srinivas Talabattula, Associate Professor, Indian Institute of Science

● Malaysia

Howe Yin Loo, Intel Microelectronics (M) Sdn. Bhd.

● Singapore

Dr. Dim-Lee Kwong, Executive Director, Institute of Microelectronics

● Taiwan

Prof. Shen-Li Fu, I-Shou University

